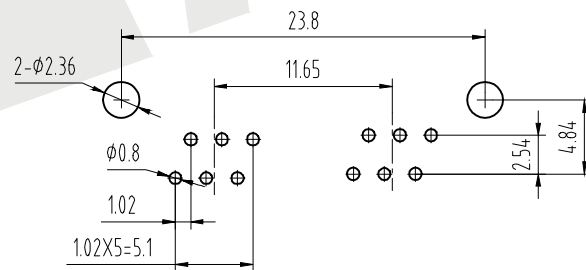
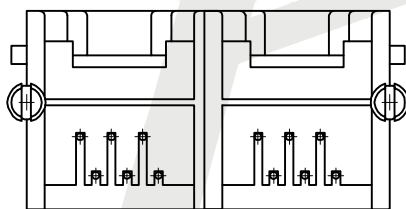
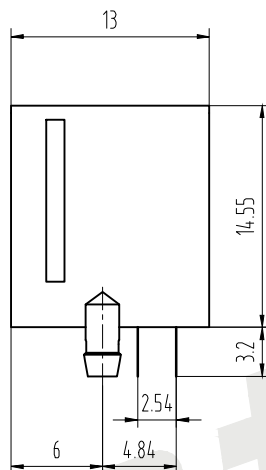
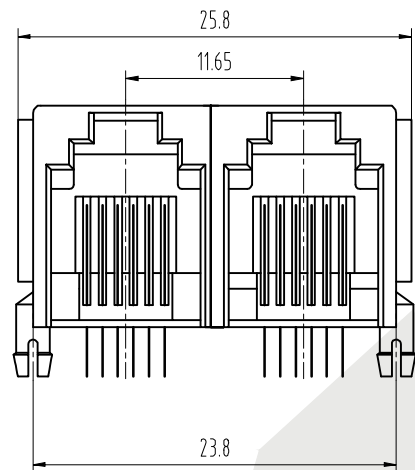


HSF



PC Board Layout  
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

ATRJ5522 - 6P - 6C - X - A - B - A

①      ②      ③      ④      ⑤      ⑥      ⑦

① SERIES NO:

② NUMBER OF POSITIONS (8P, 6P, 4P)

③ NUMBER OF CONTACTS (8C, 6C, 4C)

④ Contact Plating

- G0: Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3: 10U" Gold
- G4: 15U" Gold
- G5: 30U" Gold
- SN: Tin

⑤ Shield

- A: W/O Shield
- B: Half Shield
- C: Shield W/Eml
- D: Shield W/O Eml

⑥ Ports

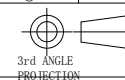
- A: 1X1P
- B: 1X2P
- C: 1X4P
- D: 1X5P
- E: 1X6P
- F: 1X8P

⑦ With Panel or not

- A: With panel
- B: Without panel

Unless Otherwise specified tolerance  
 X.  $\pm 0.35$     X.XX:  $\pm 0.20$   
 X.X:  $\pm 0.25$     X.XXX:  $\pm 0.15$

SCALE: As Shown    UNIT: mm  
 DRAW Wu Feng Rong    DATE 07/09/2019  
 CHECK BobYang    DATE 07/09/2019



**Antenk**® ANTENK ELECTRONICS CO., LTD  
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 E-mail: sales@antenk.com

TITLE: RJ11 Jack side entry,  
Full Plastic with panel, 1X2P

DRAWING NO: ATRJ5522-6P6C-X-A-B-A

PRODUCT NO: ATRJ5522-6P6C-X-A-B-A

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		